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Comments:

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U.S. Patent Application Serial No. 10/664,783

For: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING

TRENCHES OR VIAS WITH DUMMY STRUCTURES

By: Hui WANG et al.

Our Reference: 49515-20006.10

Attached is the following:

- 1. Transmittal (1 page)
- 2. Amendment Under 37 CFR 1.116 (5 pages)

sf-1973847

Please type a plus sign inside this box	• •	Ar U.S. Patent and Tred	PTO/SE/21 (08-00) proved for use through 10/31/2002. OMB 0651-8031 tenterk Office: U.S. DEPARTMENT OF COMMERCE	
Order in: Hapenwork Reduction Act of	1×35 the betegnia 819 test	Application Number	information unless it displays a yalid OMB control number. 10/664,783	
TRANSMITT	AL	Filing Date	September 16, 2003	
FORM (to be used for all correspondence after initial filing)		First Named Inventor	Hui WANG	
		Group Art Unit	2823	
		Examiner Name	M. Estrada	
Total Number of Pages In This Submiss	Total Number of Pages in This Submission 6		er 495152000810	
	ENCLOS	URES (check all	that apply)	
Fee Transmittal Form	Assignment i		After Allowance Communication to Group	
Fee Attached	Drawing(s)		Appeal Communication to Board of Appeals and Interferences	
X Amendment/Reply (5 pages)	Licensing-related Papers		Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)	
X After Final	Petition		Proprietary Information	
Affidavits/declaration(s)	Petition to Convert to a Provisional		Status Letter	
Extension of Time Request .	Power of Attorney (1 page) Revocation		X Other Enclosure(s) (place Identify below)	
Express Abandonment Request	Terminal Dis	rrespondence Address cialmer	Facsimile Cover Sheet	
Information Disclosure Statement	Request for Refund			
Certified Copy of Priority Document(s)	CD, Number of CD(6)			
Response to Missing Parts/ Incomplete Application	Remarks			
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I hereby certify that this correspondence is being facsimile transmitted to the Petent and Trademark Office, facsimile no. (571) 273-6300, on the date shown below. Dated: July 28, 2005 Signature: Valence Cohen)				
Dated: <u>July 28, 2005</u>	Signatur	: VUXIII	(Valerie Cohen)	

Art Unit: 2823

Examiner: M. Estrada

JUL 2 6 2005

REPLY UNDER 37 CFR 1.116 EXPEDITED PROCEDURE TECHNOLOGY CENTER 2800 Docket No.: 495152000610

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Dated: July 28, 2005 Signature: VA Course Carlo (Valerie Cohen)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Hui WANG et al.

Application No.: 10/664,783

Filed: September 16, 2003

For: ELECTROPOLISHING METAL LAYERS ON WAFERS HAVING TRENCHES OR VIAS

WITH DUMMY STRUCTURES

AMENDMENT UNDER 37 CFR 1.116

MS AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

This is in response to the final Office Action dated May 26, 2005 (Part of Paper No./Mail Date 20050517), for which a response is due on August 26, 2005. Accordingly, this response is timely filed. Additionally, this response is filed within two months of the mailing date of the Final Office Action and therefore qualifies for expedited review. Reconsideration and allowance of the pending claims in light of the remarks presented herein are respectfully requested.

SF-1973840